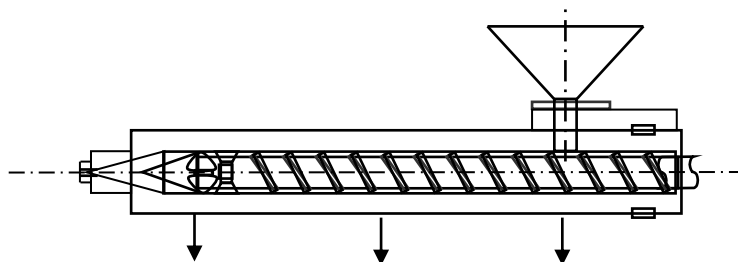


Processing Guides for WONDERLITE® PC-540

- A Pre-drying 90°C x 4 hrs
depending on
- a) Humidity
 - b) Storage conditions
 - c) Dryer's performance

B. Barrel Setting Profile

Grade / Application		Nozzle	Compression zone	Feeding zone	Mold Temperature *
PC-540	max.(°C)	240	250	220	50 -100
	min.(°C)	220	230	200	

- * varying with
- a) Thickness of molded articles
 - b) Cooling system design
 - c) Gate and runner system

NOTE :

1. Keep the resin from dust and contamination during handling and production.
2. Do not retain the hot melt at the barrel for a long time between injection cycles.
3. Temperature setting of manifold system should not exceed 270°C to avoid melt from degrading.

Purging:

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Heat decomposing resin are not recommended for purging the residual WONDERLITE and WONDERLOY in barrel of injection machine and extruder. Polyethylene and polypropylene are the most commonly used heat stable resins for purging purpose.

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